SPECIFICATION FOR APPROVAL

DESCRIPTION: Pitch 0.60mm IDC Wire To Board Connector,, R/A,SMT ,Header

CUSTOMER PROD.NO/DWG.NO:

E&T PROD.NO:

4251K-XXXN-XXX

APPROVAL SHEET NO:

E&T DWG. NO./DOCUMENT:

4251K-XXXN-XXX

REV: A4

PLEASE RETURN TO US ONE COPY OF"SPECIFICATION FOR APPROVAL"WITH YOUR APPROVED SIGNATURES.

APPROVED SIGNATURES					



ENTERY INDUSTRIAL CO., LTD. E&T ELECTRONICS (DONG GUAN) CO., LTD. E&T ELECTRONICS (SU ZHOU) CO., LTD.



Title : Pitch 0.60mm IDC Wire To Board Connector, R/A, SMT Type Header

RE	REN140109 Title: Pitch 0.60mm IDC Wire To Board Connector, R/A,SMT Type,Header				
A4	2014/1/20		This Document Contains Information That Is Proprietary To		
Rev	Description	E&T.	E&T And Should Not Be Used Without Written Permission		
Document	No.		Prepared By: Max Lee	Date: 01.13'2010	
4251K-XXXN-XXX		-XXX	Checked By: Date: Date:		
			Approved By:	Date:	

GROUP AND TEST SEQUENCE

	Test of Examination				,	Test	t Gr	oup)			
	Test of Examination		В	С	D	Е	F	G	Н	Ι	J	Κ
1	Examination of Product	1,9	1,6	1,5	1,5	1,5	1,3	1,3	1,3	1,5	1,5	
2	Contact Resistance	2,6	2,5	2,4	2,4	2,4				2,4	2,4	
3	Insulation Resistance	3,7										
4	Dielectric Strength	4,8										
5	Insertion Force And Withdrawal Force		3									
6	Terminal / Housing Retention Force											1
7	Durability		4									
8	Vibration			3								
9	Heat Resistance				3							
10	Cold Resistance					3						
11	Humidity	5										
12	Solder Ability						2					
13	Resistance To Soldering Heat							2				
14	Steam Aging		Ì						2	Ì		
15	Salt Spray									3		
16	Temperature Cycling										3	

ENTERY INDUSTRIAL CO., LTD. PRODUCT SPECIFICATION

1. SCOPE :

This specification covers the 0.6 mm pitch IDC Wire To Board connector Header series.

2. PRODUCT NAME AND PART NUMBER :

Product Name	E&T Part Number
0.60mm IDC Wire To Board Connector, R/A,SMT Type,Header	4251K-XXXN-XXX

3. RATINGS :

Item	Standard	
Rated Voltage (MAX.)	30V	AC/DC
Rated Current (M.)	0.2A (AWG#36)	
Ambient Temperature Range	-25°C ~ +85°C	

*Including temperature rise in applying electrical current

4.PERFORMANCE :

4-1 Electrical Performance

	Item	Test Condition	Requirement	
4-1-1	Contact Besistance	Test Current: 1mA(DC)InitialTest Voltage: 20mV MaxValueWire ToBe Used : AWG#36		30 mΩ Max.
4-1-1	Contact nesistance		Final Value	50 mΩ Max.
4-1-2	Insulation Resistance	Test Voltage: 100V DC. Test Duration: 1 minutes.	100 M	Ω Min.
4-1-3	Dielectric Strength	Test Voltage: 200V AC. Test After: 100V AC (Humidity & thermal		akdown

4-2 Mechanical Performance

	ltem	Test Condition	Requirement
4-2-1	Insertion Force And Withdrawal Force	Test Speed: 1 To 5mm/sec.	See 5-1
4-2-2	Terminal / Housing Retention Force	Test Speed:1 To 5mm/sec.	0.15Kgf (Min)

4-3 Environmental Performance and Others

	Item	Test Condition	Require	ment
		The contacts of connector shall be subject to 30	Contact Re	sistance
4-3-1	Durability	cycles of mating and unmating.	Initial Value	\leq 30 m Ω
			Final Value	\leq 50 m Ω
4-3-2	Vibration	Amplitude: 1.5mm Frequency range: 10~55~10Hz/minute	Appearance	No Damage
+ 0 2	Vibration	Direction: 2 hours in each X.Y.Z axes	Contact Resistance	\leq 50 m Ω
4-3-3	Heat	Temperature: 85±2°C Duration: 96 hours	Appearance	No Damage
4-0-0	Resistance		Contact Resistance	\leq 50 m Ω
4-3-4	Cold	Temperature: -25±2℃ Duration: 96 hours	Appearance	No Damage
4-3-4	Resistance		Contact Resistance	\leq 50 m Ω
		Temperature: 40±2℃ Relative Humidity: 90~95%	Appearance	No Damage
		Duration: 96 hours	Contact Resistance	\leq 50 m Ω
4-3-5	Humidity		Insulation Resistance	\geq 100M Ω
			Dielectric Strength	Must meet 4-1-3
4-3-6	Solder Ability	Soldering Time : 3 ± 0.5 sec Solder Temperature : $245\pm5^{\circ}$ C	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes

	Item	Test Condition	Requi	rement
4-3-7	Resistance To Soldering Heat	Soldering Time : 10±0.5 sec Solder Temperature : 260±5℃	Appearance	No Damage
		Steam Aging Temperature : $98\pm2^{\circ}$ C Duration: 8 hours Solder Temperature : $245\pm5^{\circ}$ C	Appearance	No Damage
4-3-8	Steam Aging	Soldering Time : 3±0.5 sec	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-8	Salt Spray	Chamber Temperature : $35\pm2^{\circ}$ C Air Tank Temperature : $47\pm1^{\circ}$ C Salt Solution : 5 ± 0.5% Duration : 48 hours	Appearance	No Damage
+ 0 0	Gail Opray	(For Contact)	Contact Resistance	\leq 50 m Ω
4-3-9	Temperature	5 cycles of : a) - 55 ±3℃ 30 minutes b)+ 85 ±2℃ 30 minutes	Appearance	Must meet
4-0-9	Cycling		Contact Resistance	4-3-5

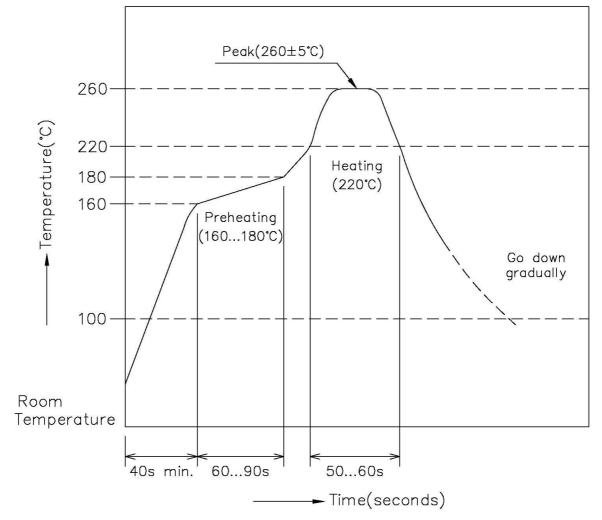
5-1

Unit:kgf

			Officingi
PIN No.	At i	nitial	At 30th
	I.F(Max)	W.F(Min)	W.F(Min)
2	1.0	0.10	0.050
3	1.0	0.15	0.075
4	1.0	0.20	0.100
5	1.0	0.25	0.125
6	2.0	0.30	0.150
7	2.0	0.35	0.175
8	2.0	0.40	0.200
9	2.0	0.45	0.225
10	2.0	0.50	0.250
11	2.5	0.55	0.275
12	2.5	0.60	0.300
13	2.5	0.65	0.325
14	2.5	0.70	0.350
15	2.5	0.75	0.375
16	3.5	0.80.	0.400
17	3.5	0.85	0.425
18	3.5	0.90	0.450
19	3.5	0.95	0.475
20	3.5	1.00	0.500

INFRARED REFLOW CONDITION

- 1) Ascending time to preheating temperature 170°C shall be 40 seconds minimum.
- 2) Preheating shall be fixed at 160...180°C for 60...90 seconds.
- 3) Heating shall be fixed at 220°C for 50...60 seconds.
- 4) At 260 \pm 5°C peak shall be 10 seconds maximum.



Wire To Board Handling Precautions

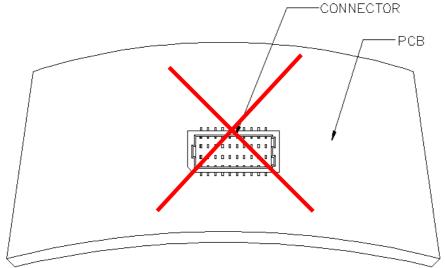
This manual is to describe basic precautions. When there are doubtful points in use of, please contact E&T.

1. Common Handling Precautions

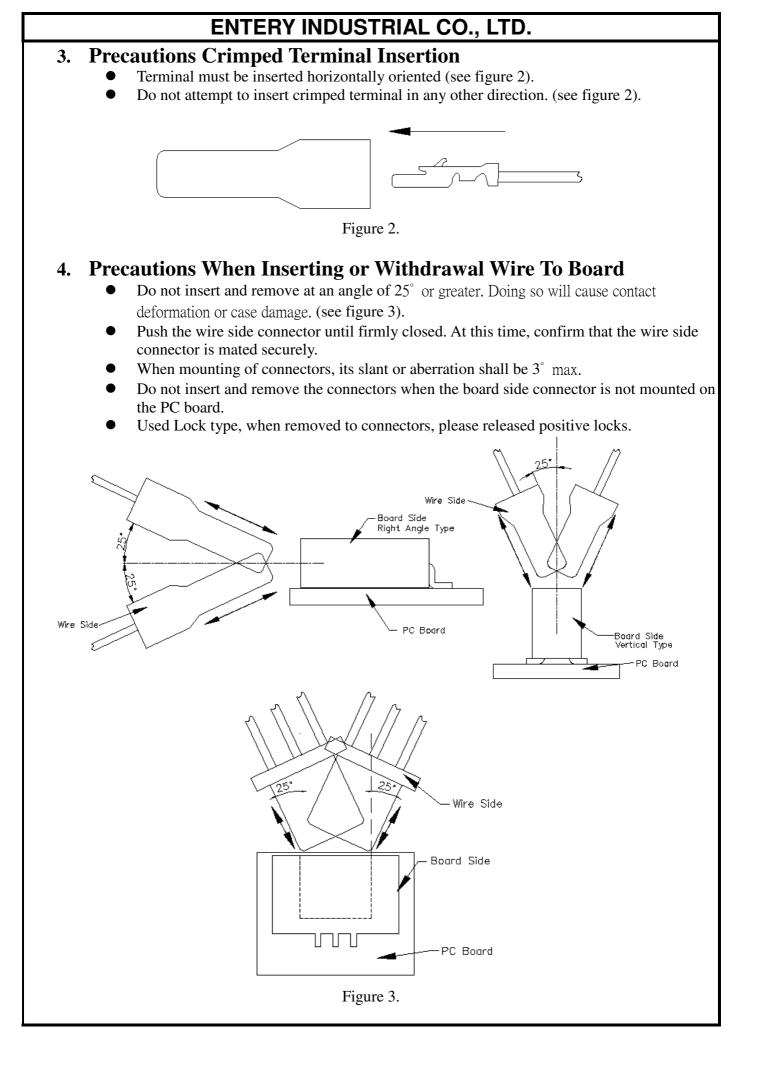
- Do not expose E&T's wire to board connector, processing process product and processing product to corrosive substance, corrosive gas, high temperature and high humidity and direct sunshine. It causes corrosion of contact and deterioration of insulation performance of housing, etc., so that it causes motion defect of appliances.
- Do not apply external load to E&T's wire to board connector, processing process product and processing product . Deformation and breakage, etc. occur, and it causes performance defect of.
- There may be slight differences in the housing coloring, but there will be no influence on the product's performance.
- Please do not conduct any "washing process" on the connector because it may damage the product's function.
- E&T's wire to board connector is not designed for the mating and unmating of the connectors to be performed under the condition of an active electrical circuit. It may cause a spark and product defect if the connectors are mated and unmated in this way.

2. PC Board Precautions

- Exercise caution when handling boards with the connectors installed. Do not apply any forces affecting soldered joints. (see figure 1).
- The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board. (see figure 1).
- Changing recommended pattern causes problems.

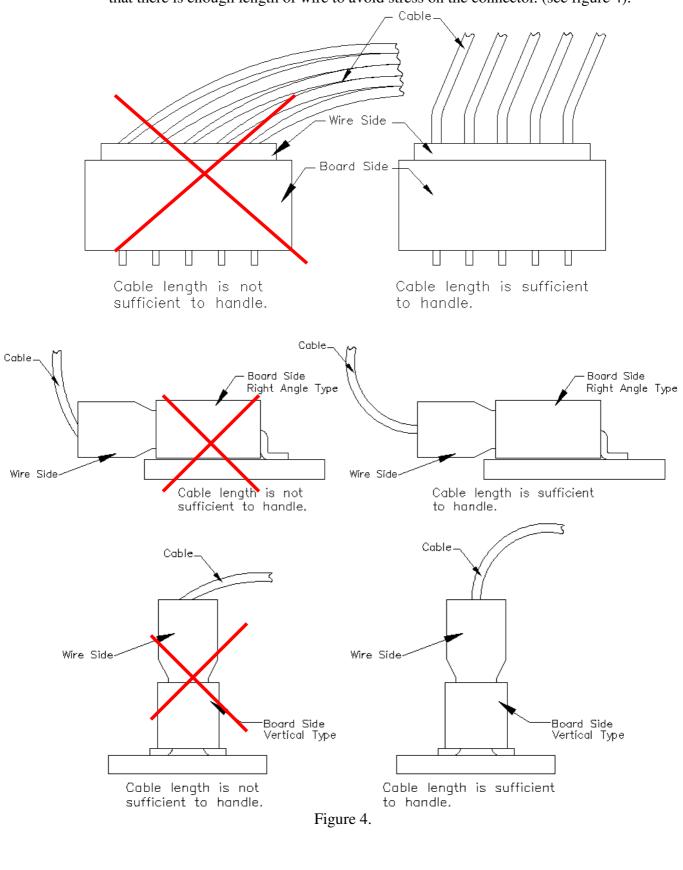






5. Precautions Cable Assembly

• The cable assembly should not have a constant stress or pulling force applied on it when it is in the mated condition. Therefore, when designing the wire positioning, please ensure that there is enough length of wire to avoid stress on the connector. (see figure 4).



ENTERY INDUSTRIAL CO., LTD. RELEASE HISTORY

Rev.	Revisions	Date	Executor	Description
	RE201110012			Add Handing Precautions
A2	RE201111014	Oct-18-2011	Max	LCP 6130LX Change LCP E130I
	RE201111028			Cancel Packaging Spec
A3	REN120904	SEP-10-2012	Max	ADD PIN Insertion Force And
AS	KEN120904	SEF-10-2012	IVIAX	Withdrawal Force (for table 5-1)
A4	REN140109	JAN-20-2014	Juno	Modify 4-3-9 5 cycles